2SD2358

Silicon NPN epitaxial planar type

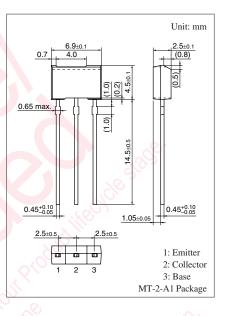
For low-frequency output amplification Complementary to 2SB1538

Features

- Low collector-emitter saturation voltage $V_{CE(sat)}$: < 0.15 V
- Allowing supply with the radial taping

Absolute Maximum Rating			
Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V _{CBO}	10	v
Collector-emitter voltage (Base open)	V _{CEO}	10	V
Emitter-base voltage (Collector open)	V _{EBO}	5	V
Collector current	I _C	1	A
Peak collector current	I _{CP}	1.2	А
Collector power dissipation *	P _C	1	W
Junction temperature	Tj	150	°C
Storage temperature	T _{stg}	-55 to +150	°C





Note) *: Printed circuit board: Copper foil area of 1 cm² or more, and the board thickness of 1.7 mm for the collector portion

Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Мах	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu A, I_{\rm E} = 0$	10	0-		V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 \text{ mA}, I_{\rm B} = 0$	10			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 7 V, I_E = 0$			1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 2 V, I_C = 100 mA$	200		800	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 500 \text{ mA}, I_{\rm B} = 20 \text{ mA}$			0.15	V
Transition frequency	f _T	$V_{CB} = 5 \text{ V}, I_E = -50 \text{ mA}, f = 200 \text{ MHz}$		120		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 20 \text{ V}, I_E = 0, f = 1 \text{ MHz}$		30		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

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